

Filename: PMP5518REVB_bom.xls							
Date: 07/21/2010							
PMP5518REVB BOM							
COUNT	RefDes	Value	Description	Size	Part Number	MFR	Area
6	C1	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106M	TDK	83,600
	C2	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106M	TDK	83,600
	C3	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106M	TDK	83,600
	C4	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106M	TDK	83,600
	C5	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106M	TDK	83,600
1	C6	470nF	Capacitor, Ceramic, 25V, X7R, 15%	0603	C1608X7R1E474M	TDK	5650
	C7	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106M	TDK	83,600
3	C8	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225M	TDK	83,600
	C9	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225M	TDK	83,600
	C10	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225M	TDK	83,600
1	C11	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	C1608X7R1C105M	TDK	5650
1	C12	220pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	std	std	5650
1	C13	220nF	Capacitor, Ceramic, 16V, X7R, 10%	0603	std	std	5650
1	C14	4.7nF	Capacitor, Ceramic, 50V, X7R, 5%	0603	std	std	5650
1	C15	330pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	std	std	5650
1	C16	470pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	std	std	5650
1	C100	100uF	Capacitor, Electrolytic, SMT, 100uF, 35V, 125c	0.457 x 0.406, 10.0x10.2mm	EEETG1V101P	Panasonic	225,848
1	C101	33uH	Capacitor, Electrolytic, SMT, 33uF, 100V, 125c	0.457 x 0.406, 10.0x10.2mm	EEETG2A330P	Panasonic	225,848
1	D1	10WT10FN	Diode, Dual Schottky, 10-A, 100-V	DPAK	10WT10FN	Vishay	107500
1	D2	68V	Diode, Zener, 68-V, 225-mW, 5%	SOT23	MMBZ5266-V	Vishay	14105
2	J1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	141600
	J2	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	141600
4	J201	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins	20000
	J202	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins	20000
	J203	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins	20000
	J204	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins	20000
2	L1	33uH	Inductor, SMT, 2.3Arms, 62milliohm, HT	0.484 x 0.484 inch	MSS1278T-333ML	Coilcraft	269,336
	L2	33uH	Inductor, SMT, 2.3Arms, 62milliohm, HT	0.484 x 0.484 inch	MSS1278T-333ML	Coilcraft	269,336
1	Q1	MMBT2222A	TRANSISTOR, NPN, HIGH-PERFORMANCE, 500mA	SOT-23	MMBT2222A	Fairchild	14105
1	Q2	BSC265N10LSFG	MOSFET, NChannel, 100V, 6.5A, 27milliohm	PWRPAK S0-8	BSC265N10LSFG	Vishay	85057
1	Q3	MMBT2907ALT1	Transistor, PNP, -60V, -600mA, 225-W	SOT23	MMBT2907ALT1	On Semi	14105
2	Q201	Si9926CDY	XSTR, MosFet, Dual N-Chan, 20V, 8.2A, Rds 0.02 ohm	SO-8	Si9926CDY	Vishay	75900
	Q202	Si9926CDY	XSTR, MosFet, Dual N-Chan, 20V, 8.2A, Rds 0.02 ohm	SO-8	Si9926CDY	Vishay	75900
1	R1	4.7	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R2	249k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R3	3.24	Resistor, Chip, 1/2W, 1%	1812	Std	Std	38080
1	R4	1k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R5	0.015	Resistor, Chip, 1/2W, 1%	1812	Std	Std	38080

2	R6	OPEN	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R7	40.2k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R8	10k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R9	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
	R10	OPEN	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R100	3.3	Resistor, Chip, 1/16W, x%	0603	Std	Std	5,650
1	R201	2.94	Resistor, Chip, 1/2W, 1%	1812	Std	Std	38080
1	R202	1.47	Resistor, Chip, 1/2W, 1%	1812	Std	Std	38080
1	R203	0.732	Resistor, Chip, 1/2W, 1%	1812	Std	Std	38080
1	R204	0.357	Resistor, Chip, 1/2W, 1%	1812	Std	Std	38080
4	R205	100k	Resistor, Chip, 1/16W, 5%	0603	Std	Std	5,650
	R206	100k	Resistor, Chip, 1/16W, 5%	0603	Std	Std	5,650
	R207	100k	Resistor, Chip, 1/16W, 5%	0603	Std	Std	5,650
	R208	100k	Resistor, Chip, 1/16W, 5%	0603	Std	Std	5,650
2	TP1	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone	10
2	TP2	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
1	TP3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone	10
	TP4	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone	10
	TP5	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
3	TP6	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
	TP7	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
	TP8	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
1	U1	TPS40211-Q1	IC, 4.5V-52V I/P, Current Mode Boost Controller	DGQ10	TPS40211QDGQRQ1	TI	38400
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.						
	2. These assemblies must be clean and free from flux and all contaminants.						
	Use of no clean flux is not acceptable.						
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.						
	4. Ref designators marked with an asterisk (***) cannot be substituted.						
	All other components can be substituted with equivalent MFG's components.						

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